

GUJARAT TECHNOLOGICAL UNIVERSITY

BE- SEMESTER-VII (NEW) EXAMINATION – WINTER 2024

Subject Code:3171107

Date:16-12-2024

Subject Name: Introduction to MEMS

Time:10:30 AM TO 01:00 PM

Total Marks:70

Instructions:

1. Attempt all questions.
2. Make suitable assumptions wherever necessary.
3. Figures to the right indicate full marks.
4. Simple and non-programmable scientific calculators are allowed.

		Mark s
Q.1	(a) What Are MEMS?	03
	(b) Why silicon so strongly associated with MEMS?	04
	(c) Define the role of actuators and sensors in the context of MEMS.	07
Q.2	(a) List out the basic MEMS materials.	03
	(b) Explain Thermal Growth Deposition.	04
	(c) What is Thick-Film Screen Printing? Explain in details.	07
	OR	
	(c) Explain the Electroplating.	07
Q.3	(a) Compare bulk and surface micromachining.	03
	(b) What do mean by Lithography? Explain.	04
	(c) Explain Linearized Analysis of MEMS devices.	07
	OR	
Q.3	(a) Explain System level modeling approach.	03
	(b) What is wafer bonding? Explain it in detail.	04
	(c) How MATLAB and Simulink tools used in MEMS?	07
Q.4	(a) Why metal packages used in military applications?	03
	(b) What is piezoelectricity? Explain with necessary diagram.	04
	(c) What is Flip Chip? Explain its advantages.	07
	OR	
Q.4	(a) Explain Sealing Techniques used for Mechanical Sensor Packaging.	03
	(b) Explain Soldering Die Attach.	04
	(c) Explain Optical Transduction Techniques.	07
Q.5	(a) What is Q factor?	03
	(b) Which are properties of the electromagnetic wave can be altered?	04
	(c) Explain elements of smart sensors.	07
	OR	
Q.5	(a) What are Electrostatic actuators?	03
	(b) Explain block diagram of a typical resonant sensor.	04
	(c) Explain any one MEMS application in detail.	07
